Advanced Packaging Summit Agenda
April 18–19, 2024
Held at NASA Ames Conference Center

DAY 1		
8:00 – 9:00 am	**Check-In**	
9:00 – 9:20 am	**Introduction and Welcome** **Review Agenda, Expectations & logistics**	Subu Iyer, Director NAPMP Bapi Vinnakota, NAPMP
9:20 – 9:25 am	**Opening Remarks DoC**	Under Secretary Laurie Locascio
9:25 – 9:30 am	**Opening Remarks NASA**	Eugene Tu, NASA
9:30 – 9:50 am	**DARPA & National Strategy on Microelectronics Research**	Carl McCants, DARPA
9:50 – 10:10 am	**Natcast**	Deirdre Hanford, Natcast
10:10 – 10:30 am	**Break**	Break
10:30 – 11:00 am	**Semiconductor startup and investment landscape in 2024 … the worst and best of times**	Daniel Armbrust, Silicon Catalyst
11:00 –11:30 am	**NAPMP Overview**	Daniel Berger, NAPMP
11:30 - 11:50 am	**Chiplets**	Bapi Vinnakota, NAPMP
11:50 – 1:00 pm	**Lunch**	Lunch
1:00 – 3:00 pm	**Panel: Applications – HPC & AI**	Moderator: John Shalf, DOE
3:00 – 3:15 pm	**Break**	Break
3:15 – 4:30 pm	**Panel: Applications – Aerospace & Automotive**	Moderator: Scott Bukofsky, NSTC
4:30 – 5:30 pm	**Panel: Applications - Low Power**	Moderator: George Orji, NAPMP
5:30 pm	**Wrap up, Adjourn**	George Orji, NAPMP

DAY 2		
8:30 – 9:00 am	**Check-In (if needed)**	
9:00 – 9:05 am	**Review Agenda & Logistics**	NAPMP
9:05 – 9:35 am	**Semiconductors for the Future of Aerospace**	Prasun Desai, NASA
9:35 – 10:05 am	**Enabling Moore's Law's Through Heterogeneous Integration**	Raja Swaminathan, AMD
10:05 – 10:20 am	**Break**	Break
10:20 – 11:30 am	**Panel: Support for Startups**	Moderator: Daniel Armbrust, Silicon Catalyst

11:30 – 12:30 pm	**Lunch Break**	Break
12:30 – 1:45 pm	**Panel: Applications – Biomedical**	Moderator: Andy DeHennis, CHIPS R&D
1:45 – 3:00 pm	**Panel: Packaging Pilot Needs & The Path to HVM**	Moderator: Erik Hadland, SIA
3:00– 3:15 pm	**Break**	Break
3:15 – 4:15 pm	**Panel: Emerging Challenges to Advanced Packaging**	Moderator: Eric Lin, CHIPS R&D
4:15 – 5:30 pm	**Advanced Packaging Acceleration**	K.C. Hsu, TSMC
	Panel: Accelerating the Adoption of Advanced Packaging	Moderator: Bapi Vinnakota, NAPMP
5:30 pm	**Closing Remarks, Adjourn**	George Orji, NAPMP

<u>Program Committee:</u>

David LaVan (CHIPS)

Bryan Biegel (NASA)

Bapi Vinnakota (CHIPS)

Greg Yeric (CHIPS)

Matt Kelly (IPC)

Matt Walsh (DoD – ReShape)

Erik Hadland (SIA)

Andrew DeHennis (CHIPS)